

## CLAIM AMENDMENTS

Claims 1-8 (canceled)

9. (original) A method of manufacturing an electronic component comprising a contact having a terminal section for brazing and a contact section, said method comprising the steps of:

constructing a base member of said contact made of a material which is poorly wettable to a weld brazing material;

forming on said base member a finish plating layer made of a material which is highly wettable to the weld brazing material; and

forming an exposed region of said poorly wettable base member by selectively removing a portion of said highly wettable finish plating layer at said terminal section by means of a mechanical processing technique,

said exposed region of said highly wettable base material serving as an arresting region for arresting creeping-up of said weld brazing material.

10. (original) The method according to claim 9, further including the step of:

forming a primer plating layer made of a material which is poorly wettable to said weld brazing material on said base member prior to forming said finish plating layer; and wherein

the step of forming the finish plating layer is carried out to form the finish plating layer on the thus formed primer plating layer, and

the step of forming the exposed region is carried out to selectively removing both a portion of said primer plating layer and a portion of said finish plating layer by a mechanical processing technique.

11. (original) The method according to claim 9, wherein

said base member is made of copper alloy, and

said finish plating layer is made of any one of gold plating layer, tin or tin alloy plating layer, and lead or lead alloy plating layer.

12. (original) The method according to claim 10, wherein  
said base member is made of copper alloy, and  
said finish plating layer is made of any one of gold plating layer, tin or tin alloy  
plating layer, and lead or lead alloy plating layer.

13. (original) The method according to claim 10, wherein said primer plating layer is made  
of nickel alloy plating layer.

14. (currently amended) The method according to ~~any one of claim 9 to 13~~, wherein said  
mechanical processing technique is any of mechanical cutting or grinding technique, electric  
discharge machining technique, electron-beam machining technique and laser beam machining  
technique.

15. (new) The method according to claim 10, wherein said mechanical processing technique  
is any of mechanical cutting or grinding technique, electric discharge machining technique,  
electron-beam machining technique and laser beam machining technique.

16. (new) The method according to claim 11, wherein said mechanical processing technique  
is any of mechanical cutting or grinding technique, electric discharge machining technique,  
electron-beam machining technique and laser beam machining technique.

17. (new) The method according to claim 12, wherein said mechanical processing technique  
is any of mechanical cutting or grinding technique, electric discharge machining technique,  
electron-beam machining technique and laser beam machining technique.

18. (new) The method according to claim 13, wherein said mechanical processing technique  
is any of mechanical cutting or grinding technique, electric discharge machining technique,  
electron-beam machining technique and laser beam machining technique.